



US00D789311S

(12) **United States Design Patent**
Okada et al.

(10) **Patent No.:** **US D789,311 S**
(45) **Date of Patent:** **** Jun. 13, 2017**

(54) **PATTERN WAFER**

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(**) Term: **15 Years**

(21) Appl. No.: **29/569,274**

(22) Filed: **Jun. 24, 2016**

(30) **Foreign Application Priority Data**

Dec. 28, 2015 (JP) 2015-029187

(51) **LOC (10) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**

USPC D13/182; D6/309
CPC C30B 25/02; C30B 25/04; C30B 25/12; C30B 25/18; C30B 25/186; C30B 25/20; H01L 21/2018; H01L 21/2003; H01L 21/02367; H01L 21/0237; H01L 21/02428; H01L 21/0243; H01L 21/02433; H01L 21/02436; H01L 21/31116; H01L 21/32139; H01L 21/31144; H01L 21/0337; H01L 21/31138; H01L 21/02439; H01L 21/3213; H01L 21/32131; H01L 21/32133; H01L 21/32135; H01L 21/823807; H01L 21/84; H01L 21/31055; H01L 21/31053; H01L 21/76819; H01L

21/31111; H01L 33/16; H01L 29/02; H01L 29/04; H01L 29/045; H01L 29/06; H01L 29/0603; H01L 29/66765; H01L 29/66757; H01L 27/1203; H01L 27/1218; H01L 27/1222; H01S 5/3202

See application file for complete search history.

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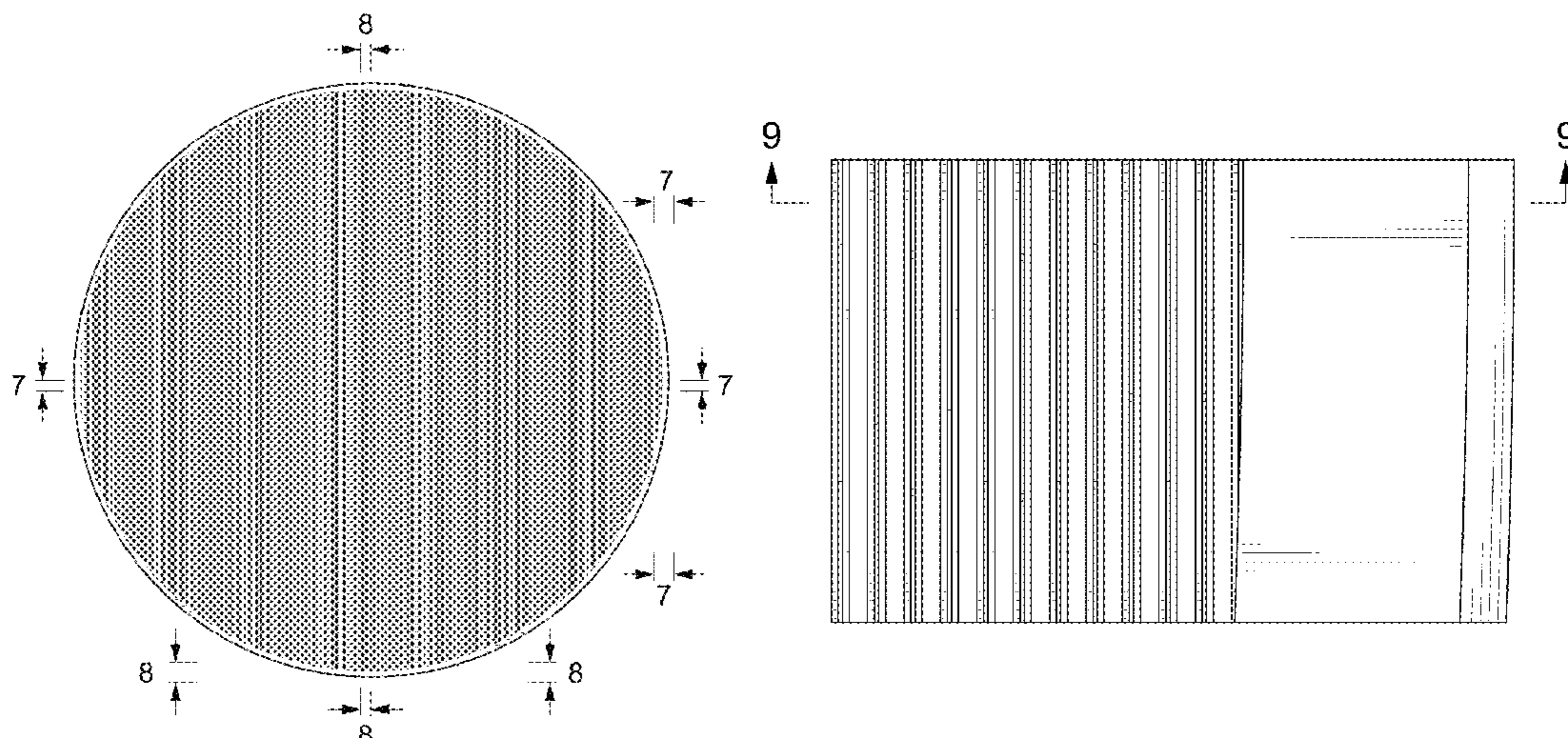
(57) **CLAIM**

The ornamental design for a pattern wafer, as shown and described.

DESCRIPTION

FIG. 1 is a front elevational view of a pattern wafer, showing our new design;
FIG. 2 is a rear elevational view thereof;
FIG. 3 is a left side elevational view thereof;
FIG. 4 is a right side elevational view thereof;
FIG. 5 is a top plan view thereof;
FIG. 6 is a bottom plan view thereof;
FIG. 7 is an enlarged front portion view taken along line 7-7 in FIG. 1;
FIG. 8 is an enlarged front portion view taken along line 8-8 in FIG. 1;
FIG. 9 is a cross sectional view taken along line 9-9 in FIG. 7; and,
FIG. 10 is a top perspective view of FIG. 8.

1 Claim, 5 Drawing Sheets



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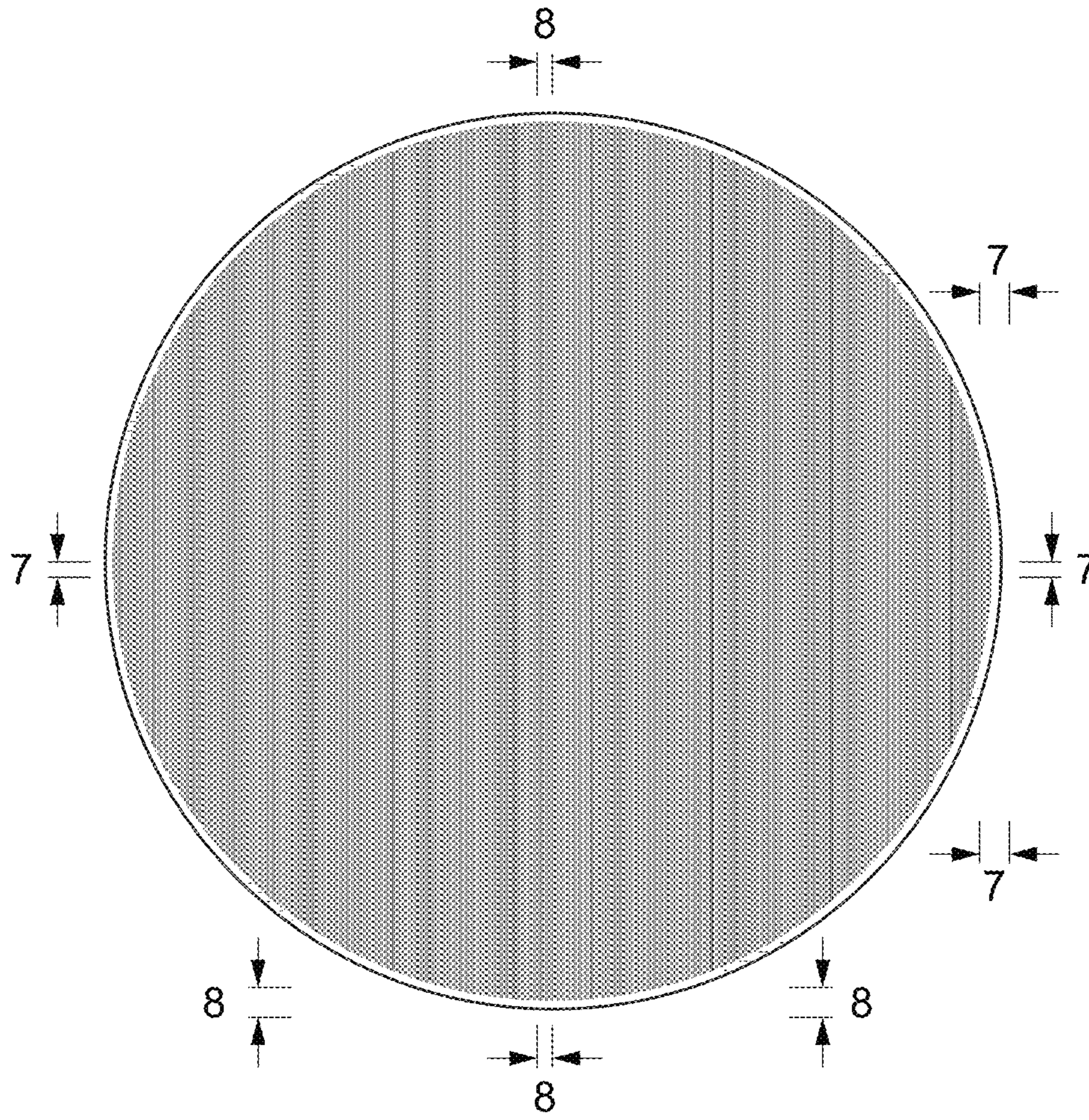


FIG. 1

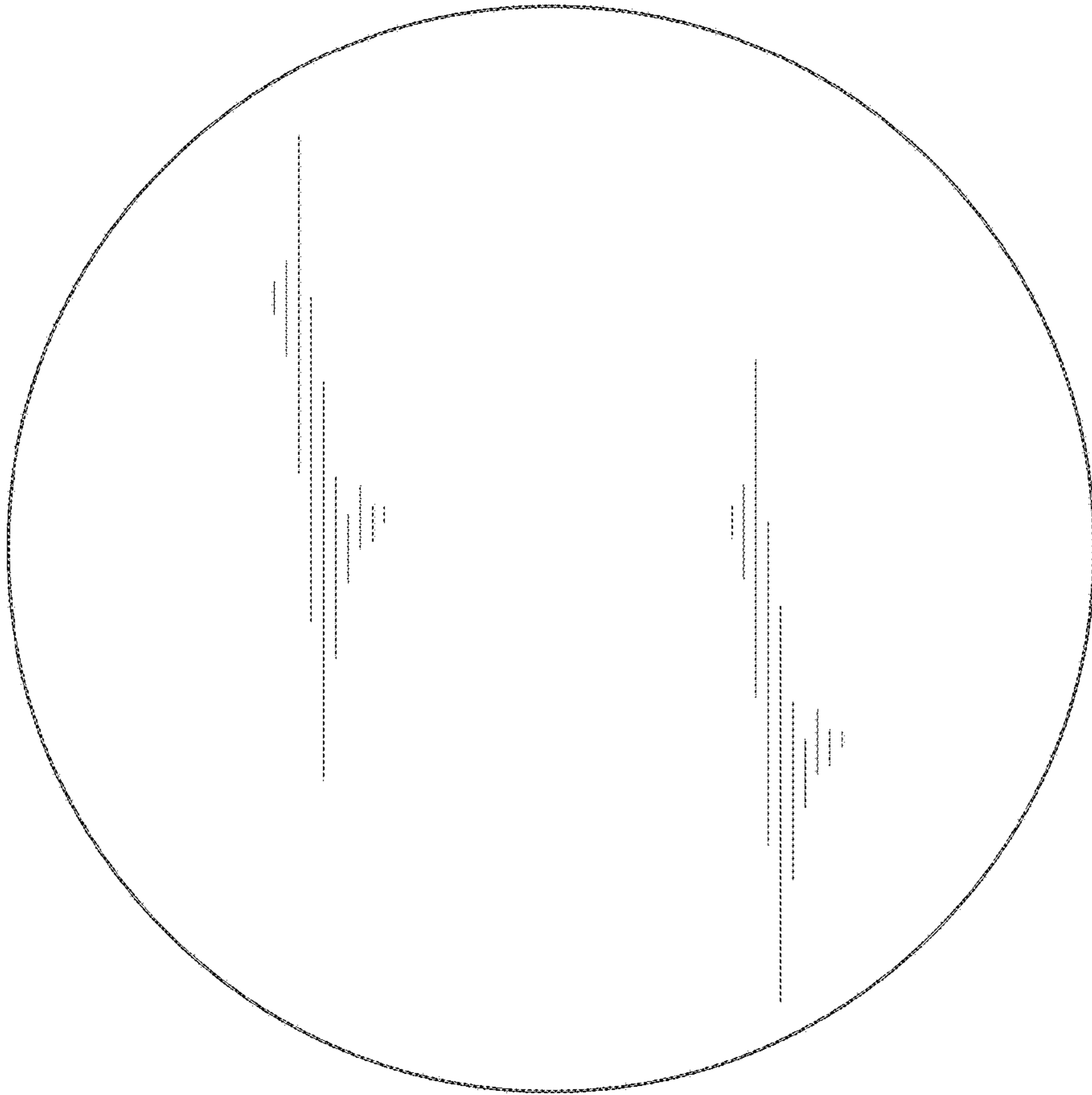


FIG. 2



FIG. 3

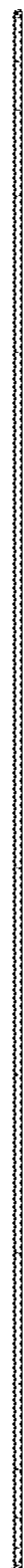


FIG. 4

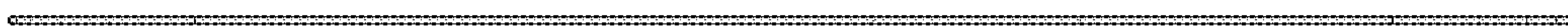


FIG. 5



FIG. 6

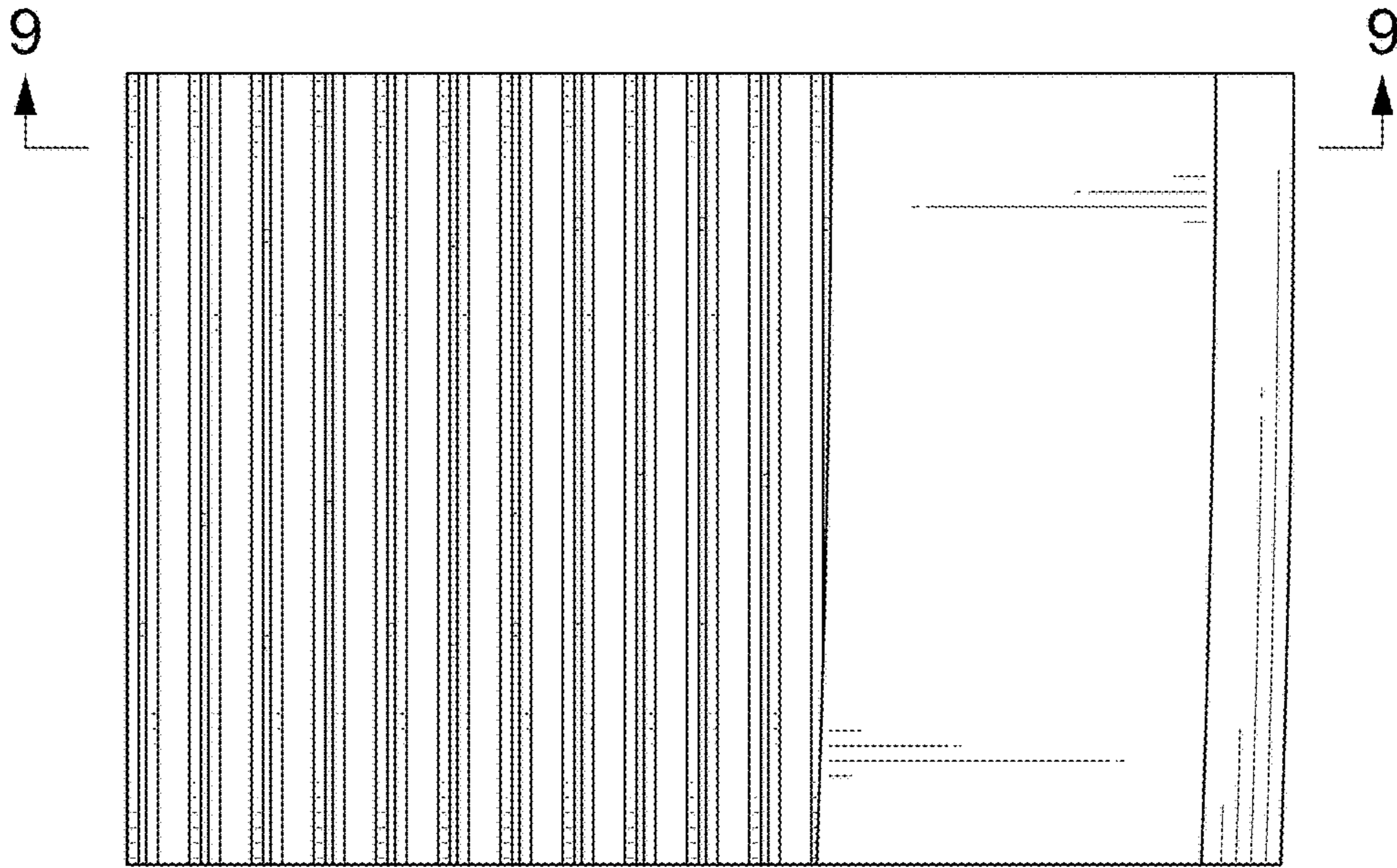


FIG. 7

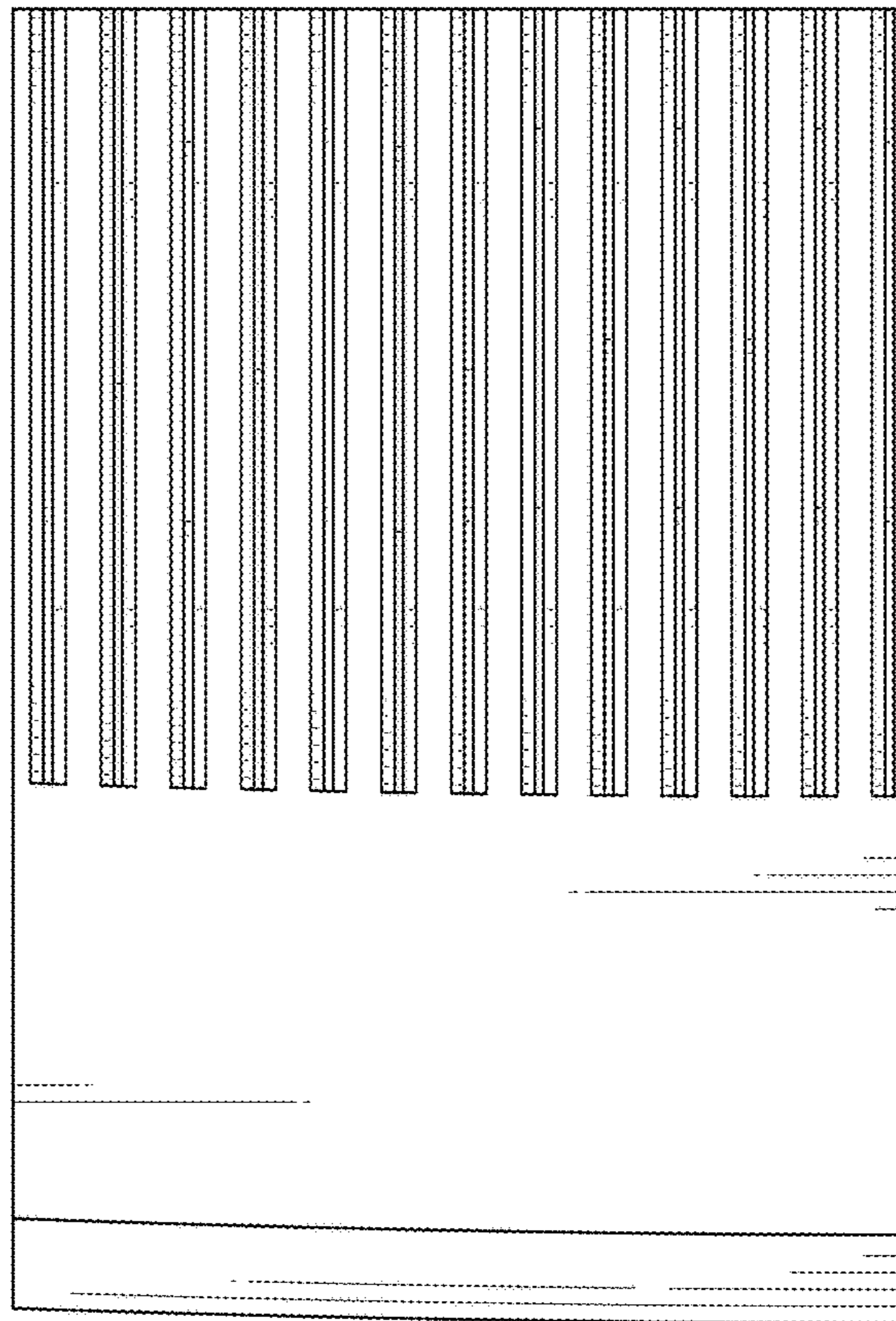


FIG. 8

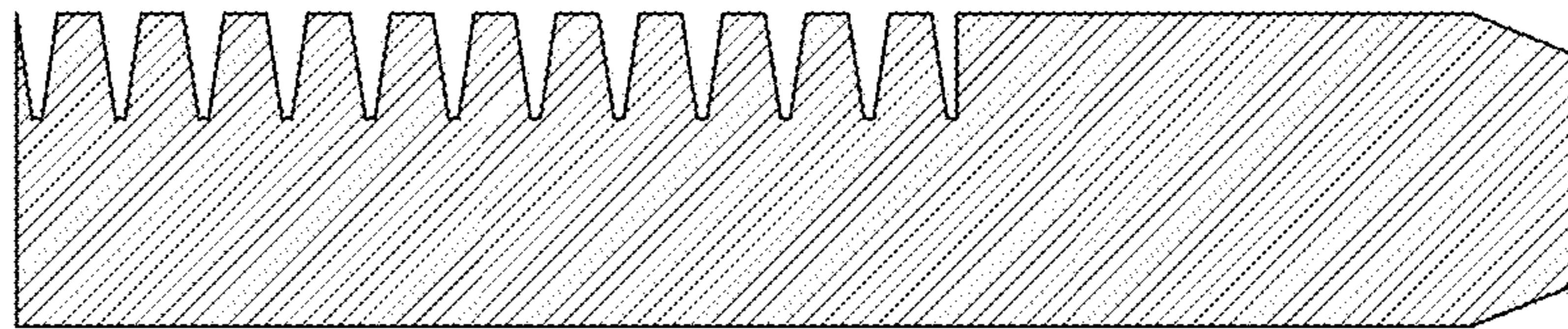


FIG. 9

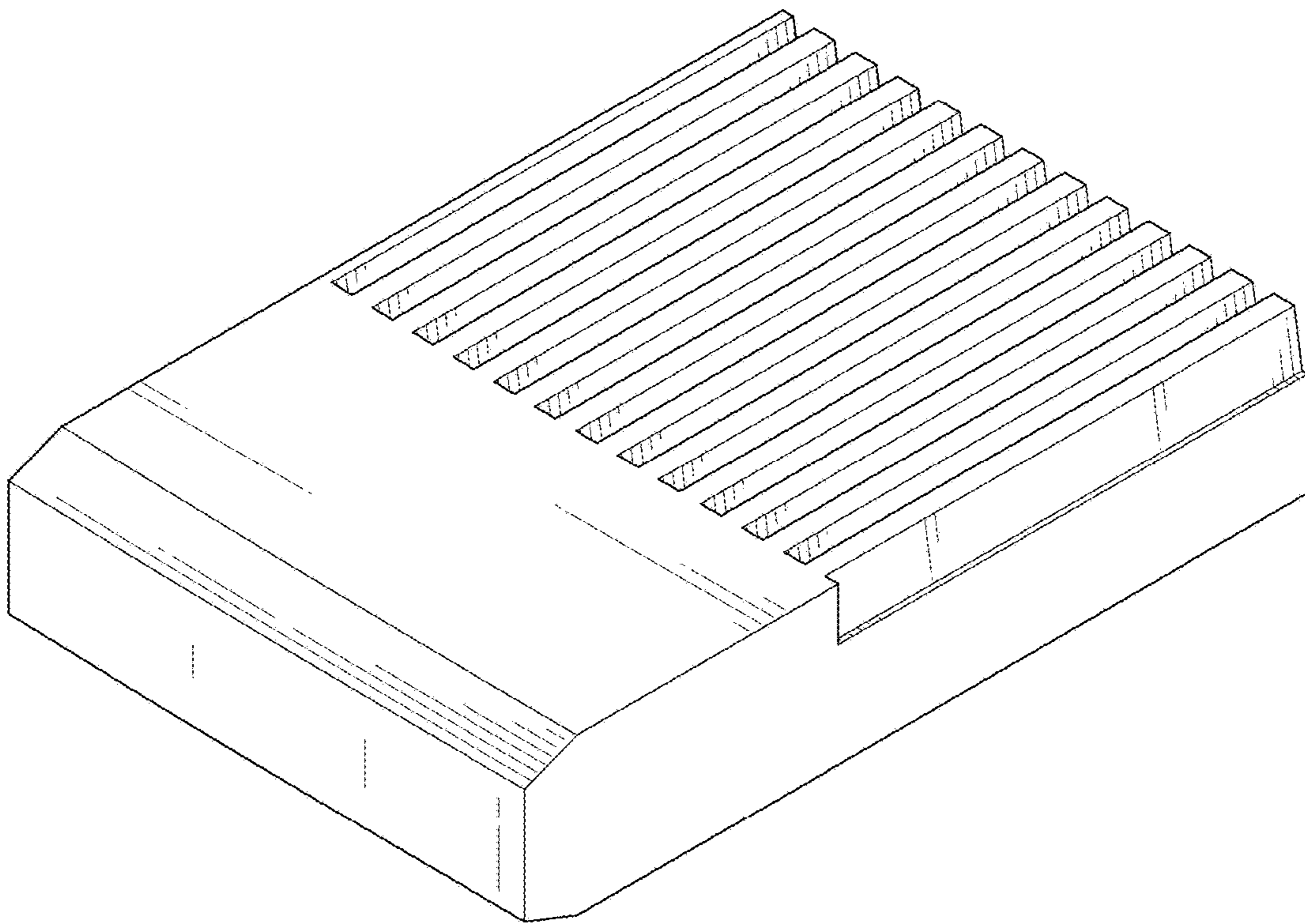


FIG. 10